

Abstract of the Disclosure

A micro leadframe package employing an oblique etching method is disclosed. The micro leadframe package includes a semiconductor chip, an oblique-etched micro leadframe (MLF) having a die pad on which the semiconductor chip is
5 mounted via adhesive means, leads formed along outer sides of the die pad, and tie bars for supporting four corners of the die pad, wires for connecting the semiconductor chip with the leads of the MLF, and an epoxy molding compound (EMC) for encapsulating the semiconductor chip, the MLF, and the wires.